

**SPAR - BRAMPTON (SSS)**  
9445 AIRPORT RD

## Critical Items List

SRMS

CIL Ref#: **2587**

BRAMPTON ONTARIO L6S4J3

Revision: 0

FMEA Rev: 0

**System:** SRMS

**Subsystem:** ELECTRICAL SUB-SYSTEM

**Assembly Desc:** Servo Power Amplifier

**Part Number(s):** 51140F1177-3                      51140F1177-5

**Item:**

**Function:** Central Processing Unit Assembly

Provides hardware and software necessary to implement servo control loops, control operation of the Analog I/F, Digital I/F and MDA boards and communicate with the MCIU. Provides PLL and frame sync BITE as well as a hardware watchdog timer to monitor health of microcomputer itself.

Digital Interface Assembly

Receives and loads command data to CPU. Generates position encoder clock and sync signals, processes position encoder data and external flags and assembles return data for transmission to MCIU.

**Failure Mode:** Data Echoing failure.

	<u>H/W</u>	<u>Func.</u>	<u>Screen Failures</u>
<b>Criticality:</b>	2	1	R

**Mission Phase:** Orbit

**Cause(s):** Central Processing Unit Assembly

CPU off-board I/O control DIGSEL2 fails active (low).

Digital Interface Assembly

CPU off-board I/O control DIGSEL2 fails inactive (high).

DIGSEL2 failed inactive.

Inability to clear input shift registers after read.

Loss of or erroneous data written into input data shift registers.

**Failure effect on unit/end item:**

Corrupt echoed command data words for failed joint. False ABE communication BITE will occur. All return data remains valid.

**Worst Case:** Loss of mission. Loss of computer supported modes.

**Redundant Paths:** Autobrakes (to Safe the System).

Direct Drive.

Backup Drive.

### Retention Rationale

**Design:**

The design utilizes proven circuit techniques and is implemented using CMOS logic devices. CMOS devices operate at low power and hence do not experience significant operating stresses. The technology is mature, and device reliability history is well documented. All stresses are

Field Programmable Gate Arrays (FPGA's) and the Error Detection and Correction (EDAC) are semi-custom microcircuits in which the design functional elements are designed by the manufacturer. The interconnection of these elements is then customized by Spar to provide the functionality of the completed microcircuit. The design utilizes proven circuit techniques and is implemented using CMOS technology. This technology operates at low power and hence the device does not experience significant operating stresses. The technology is mature, and the basic device reliability is well documented. All stresses are additionally reduced by derating the appropriate parameters in accordance with SPAR-RMS-PA.003 and verified by design review.

This approach has a significant advantage in that it reduces the quantity of discrete parts required in the assembly and also the complexity of the PWB and results in significant weight and volume savings. This type of semi-custom part has been successfully used in other space applications.

The parts are qualified to the requirements of the applicable specification. They are 100% screened and burned in to the requirements of this Spar requirements document.

Resistors and capacitors used in the design are selected from established reliability (ER) types. Life expectancy is increased by ensuring that all allowable stress levels are derated in accordance with SPAR-RMS-PA.003. All ceramic and electrolytic capacitors are routinely subjected to radiographic inspection in accordance with the requirements of MSFC-STD-355.

The SPA board is fabricated using Surface Mount Technology (SMT). This is a PWB assembly technology in which the components are soldered to the solder pads on the surface of the PWB. The significant advantage of this technology is to enable the parts on the board to be more densely packed, to reduce to overall volume and weight of the assembly.

The assembly process is highly automated. The parts are mounted on the boards using a computer controlled "pick and place" machine. The subsequent soldering operation is performed using a belt furnace, in which the time and temperature thermal profile that the PWB assembly is exposed to is tightly controlled and optimized to ensure proper part soldering attachment. The assembly is manufactured under documented procedures and quality controls. These controls are exercised throughout the assembly, inspection and testing of the unit. This inspection includes workmanship, component mounting, soldering, and conformal coating to ensure that it is in accordance with the NHB 5300 standards.

The SMT line used for the SPA PWB assembly has undergone a full qualification program, and assemblies produced on this line are used in other space programs.

The circuit board design has been reviewed to ensure adequate conductor width and separation and to confirm appropriate dimensions of solder pads and of component hold provisions. Parts mounting methods are controlled in accordance with MSFC-STD-154A, MSFC-STD-136 and SASD 2573751. These documents require approved mounting methods, stress relief and component security.

**Test:**

**QUALIFICATION TESTS** - The SPA is subjected to the following qualification testing:

**VIBRATION:** Each axis of the QM is subjected to Flight Acceptance Vibration Test (FAVT), Qualification Acceptance Vibration Test (QAV) and Qualification Vibration Tests (QVT) in accordance with the SPA Vibration Test Procedure (826586). The level and duration for FAVT is as per Figure 6 and Table 2 of 826586; the level and duration for QAVT is as per Figure 7 and Table 2 of 826586; the level and duration for QVT is as per Figure 8 and Table of 826586. At the end of the three successive random vibration test in each axis, both directions (+/-) of each of the axis is subjected to a shock pulse test as per Figure 9 of 826586.

**THERMAL/VACUUM:** QM TVAC Test is in accordance with Figure 5 of the SPA TVAC Test Procedure (826588), with full Functional/Parametric Test performed at levels of +60 degrees C and -36 degrees C, and non-operating at -54 degrees C. The Qualification vacuum levels during TVAC is  $1 \times 10^{-6}$  torr or less. The total test duration is 7 1/2 cycles. The QM SPA is subjected to a minimum of 1000 hours of life testing and 1000 power On-Off cycles.

**EMC:** The QM is subjected to EMC Testing (tests CE01/CE03, CE07, CS01, CS02, CS06, RE02, RS02, and RS03) in accordance with the SPA EMC test Procedure (826477) based on MIL-STD-461A.

**UNIT FLIGHT ACCEPTANCE TESTS** - The FM SPA is subjected to the following acceptance testing:

**VIBRATION:** FM Acceptance Vibration Test (AVT) in accordance with the SPA Vibration Test Procedure (826586), with level and duration as per Figure 6 and Table 2 of 826586.

**THERMAL/VACUUM:** FM TVAC Test is in accordance with Figure 6 of the SPA TVAC Test Procedure (826588), with levels of +49 degrees C and -25 degrees C for a duration of 1 1/2 cycles. The vacuum levels during Acceptance TVAC Test is  $1 \times 10^{-5}$  torr or less.

**JOINT SRU TESTS** - The SPA is tested as part of the joints (ambient and vibration tests only). The ambient ATP for the Shoulder Joint

fabrication, assembly, and test. Government source inspection is invoked at various control levels.

EEE parts inspection is performed as required by SPAR-RMS-PA.003. Each EEE part is qualified at the part level to the requirements of the applicable specification. All EEE parts are 100% screened and burned-in, as a minimum, as required by SPAR-RMS-PA.003, by the supplier. DPA is performed as required by PA.003 on a randomly selected 5% of parts, maximum 5 pieces, minimum 3 pieces for each lot number/date code of parts received. All cavity devices are subjected to 100% PIND. Wire is procured to specification MIL-W-22759 or MIL-W-81381 and inspected and tested to NASA JSCM8080 Standard Number 95A.

Receiving inspection verifies that all parts received are as identified in the procurement documents, that no physical damage has occurred to parts during shipment, that the receiving documents provide adequate traceability information and screening data clearly identifies acceptable parts.

Parts are inspected throughout manufacture and assembly as appropriate to the manufacturing stage completed. These inspections include:

Printed circuit board inspection for track separation, damage and adequacy of plated through holes, component mounting inspection for correct soldering, wire looping, strapping, etc. Operators and inspectors are trained and certified to NASA NHB 5300.4(3A-1) Standard. Conformal coating inspection for adequate processing is performed using ultraviolet light techniques. P.C. Board installation inspection includes checks for correct board installation, alignment of boards, proper connector contact mating, wire routing, strapping of wires etc. Post P.C. Board installation inspection includes cleanliness and workmanship (Spar/government rep. mandatory inspection point).

Unit Pre-Acceptance Test inspection, which includes an audit of lower tier inspection completion, as built configuration verification to as design etc (mandatory inspection point). A unit Test Readiness Review (TRR) which includes verification of test personnel, test documents, test equipment calibration/validation status and hardware configuration is convened by QA in conjunction with Engineering, Reliability, Configuration Control, Supplier as applicable, and the government representative, prior to the start of any formal testing (Acceptance or Qualification). Unit level Acceptance Testing (ATP) includes ambient performance, thermal and vibration testing (Spar/government rep. mandatory inspection point).

Integration of unit to Joint SRU - Inspections include grounding checks, connectors for bent or pushback contacts, visual, cleanliness, interconnect wiring and power up test to the appropriate Joint Inspection Test Procedure (ITP). Joint level Pre-Acceptance Test Inspection, includes an audit of lower tier inspection completion, as built configuration verification to as design etc. Joint level Acceptance Testing (ATP) includes ambient and vibration testing (Spar/government rep. mandatory inspection point).

Mechanical Arm Reassembly - the integration of mechanical arm subassemblies to form the assembled arm. Inspections are performed at each phase of integration which includes electrical checks, through wiring checks, wiring routing, interface connectors for bent or pushback contacts etc. Mechanical Arm Testing - Strongback and flat floor ambient performance test (Spar/government rep. mandatory inspection point).

OMRSD Offline: Power-up arm. Verify no ABE communication failures or BITE errors.

OMRSD Online None  
Installation:

OMRSD Online Power-up arm. Verify no ABE communication failures or BITE errors.  
Turnaround:

Screen Failure: A: Pass  
B: Pass  
C: Pass

Crew Training: The crew will be trained to always observe whether the arm is responding properly to commands. If it isn't, apply brakes.

Crew Action: Select Direct Drive. Single/Direct Drive switch should be pulsed to maintain proper rates.

Operational Effect: Computer supported modes are lost. Direct Drive and Back-up are available.

Mission None.  
Constraints:

Approvals:

Functional Group

Name

Position

Signature

Date

Time